



42390.P11992

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

James A. McCall et al.

Application No.: 09/911,752

Filed: July 23, 2001

For: SYSTEMS HAVING MODULES WITH
BUFFER CHIPS

Examiner: Tuan T. Dinh

Art Unit: 2827

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Commissioner for Patents
Washington, D.C. 20231

AMENDMENT

Sir:

This is in response to the Office action dated October 1, 2002. Reconsideration of the application is requested.

ENTIRE SET OF PENDING CLAIMS (Clean version)

1. (Amended) A system comprising:
first and second modules, the first module having a first group of chips and the second module having a second group of chips;
a circuit board including first and second module connectors to receive the first and second modules, respectively;
a first buffer on the first module and a second buffer on the second module; and
a path including conductors in a first section that splits into a second section and third section, wherein the second section couples to the first buffer and the third section couples to the